

**SOLDER ALLOY, SOLDER PASTE, SOLDER BALL, SOLDER PREFORM,
SOLDER JOINT, IN-VEHICLE ELECTRONIC CIRCUIT, ECU ELECTRONIC
CIRCUIT, IN-VEHICLE ELECTRONIC CIRCUIT DEVICE AND ECU
ELECTRONIC CIRCUIT DEVICE**

Abstract

A solder alloy comprises Ag: 3.1 to 4.0% by mass, Cu: 0.6 to 0.8% by mass, Bi: 1.5 to 5.5% by mass, Sb: 1.0 to 6.0% by mass, Co: 0.001 to 0.030% by mass, Fe: 0.02 to 0.05% by mass, and a balance Sn.

[Fig.1]